

## SB3T100

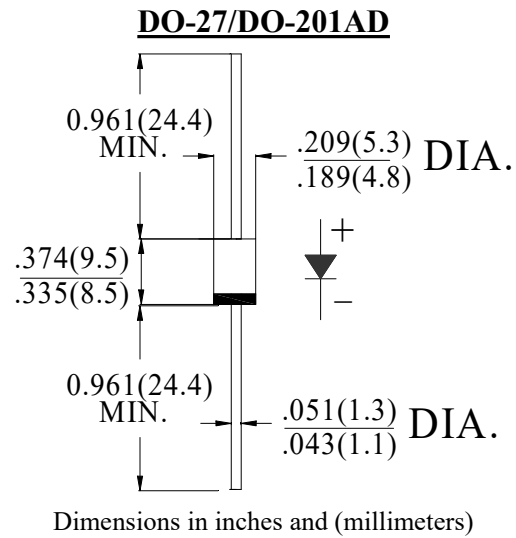
### 3.0AMPS. SCHOTTKY BARRIER RECTIFIERS

#### FEATURE

- . For surface mounted application
- . High current capability
- . Low forward voltage drop
- . Low power loss, high efficiency
- . High surge current capability
- . High temperature soldering guaranteed:  
260°C/10 seconds at terminals.

#### MECHANICAL DATA

- . Terminal: Solder plated
- . Case: Molded with UL-94 Class V-0 recognized  
Flame Retardant Epoxy (free halogen)
- . Polarity: color band denotes cathode



#### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	SYM BOL	SB3T100	units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	100	V
Maximum RMS Voltage	$V_{RMS}$	70	V
Maximum DC blocking Voltage	$V_{DC}$	100	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	3.0	A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC method)	$I_{FSM}$	80.0	A
Forward Voltage at 3.0A DC	@ $T_J=25^\circ\text{C}$	$V_{F(MAX)}$	V
		$V_{F(TYP)}$	
	@ $T_J=125^\circ\text{C}$	$V_{F(MAX)}$	
Maximum DC Reverse Current at rated DC blocking voltage	@ $T_J=25^\circ\text{C}$	$I_R$	mA
	@ $T_J=100^\circ\text{C}$		
Typical Junction Capacitance (Note1)	$C_J$	340	pF
Typical Thermal Resistance (Note2)	$R_{(JA)}$	45	°C/W
	$R_{(JL)}$	14	
Storage Temperature	$T_{STG}$	-55 to +150	°C
Operating Junction Temperature	$T_J$	-55 to +150	°C

#### Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
2. Thermal Resistance from Junction to Ambient at 0.375"(9.5mm) lead length, vertical P.C. Board Mounted

**RATING AND CHARACTERISTIC CURVES**

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

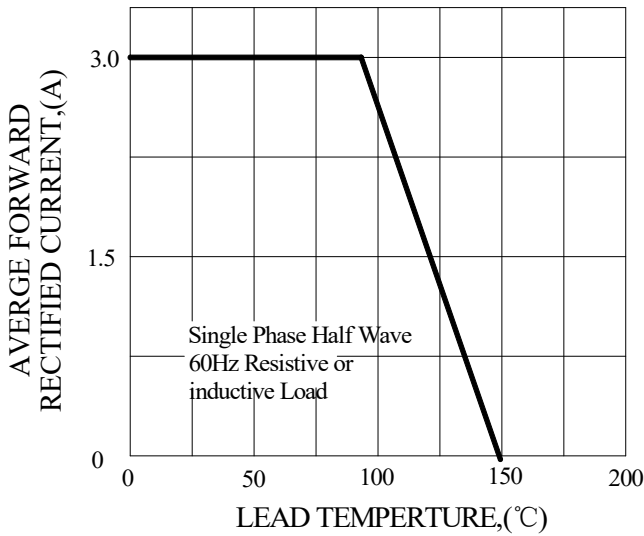


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

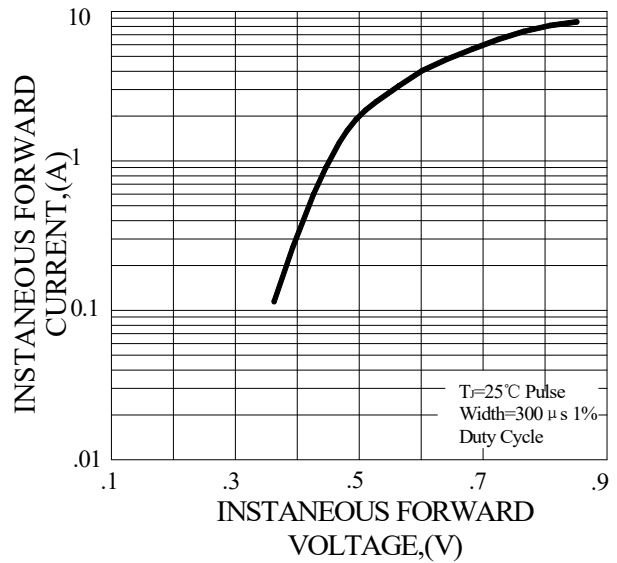


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

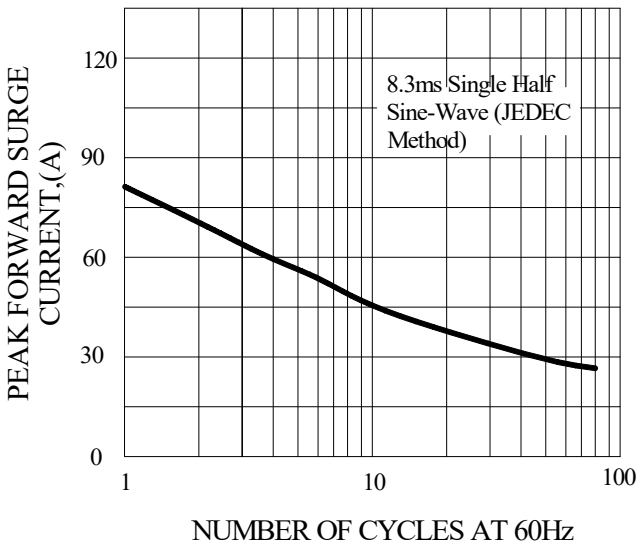
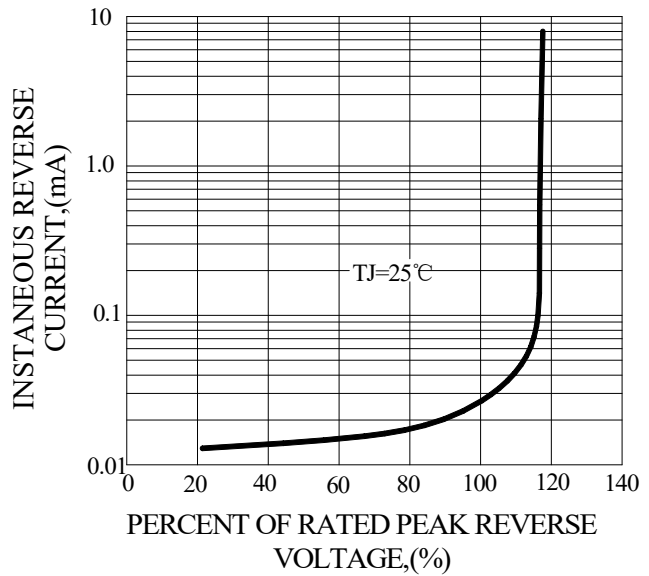
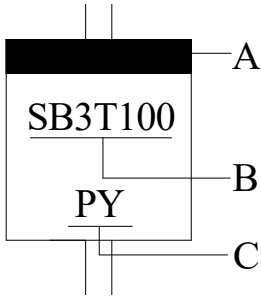


FIG.4-TYPICAL REVERSE CHARACTERISTICS



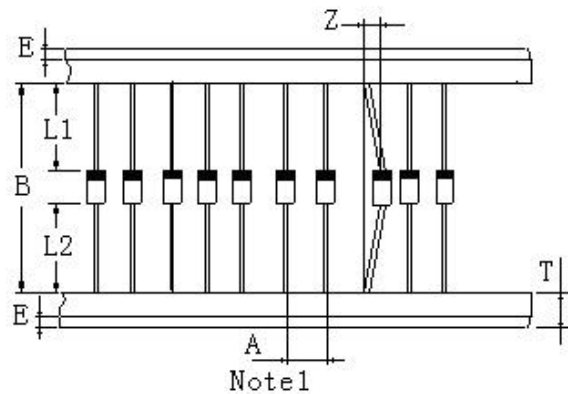
## Marking and packaging illustration

### 1、Marking



SYMBOL	Explanation
<b>A</b>	<b>Color Band Denotes Cathode</b>
<b>B</b>	<b>Product Name</b>
<b>C</b>	<b>Trademark</b>

### 2、Packaging



ITEM	SYMBOL	SPECIFICATIONS (mm)	SPECIFICATIONS (inch)
Component alignment	Z	1.2max	0.048max
Tape width	T	6.0±0.4	0.236±0.016
Exposed adhesive	E	0.8max	0.032max
Body eccentricity	L1-L2	1.0max	0.040max
Component	A	10.0±0.5	0.4±0.02
Inner tap	B	52.0~53.5	2.05~2.11

NOTE:

Each component lead shall be sandwiched between tapes for a minimum of 2.5mm (0.1inch)